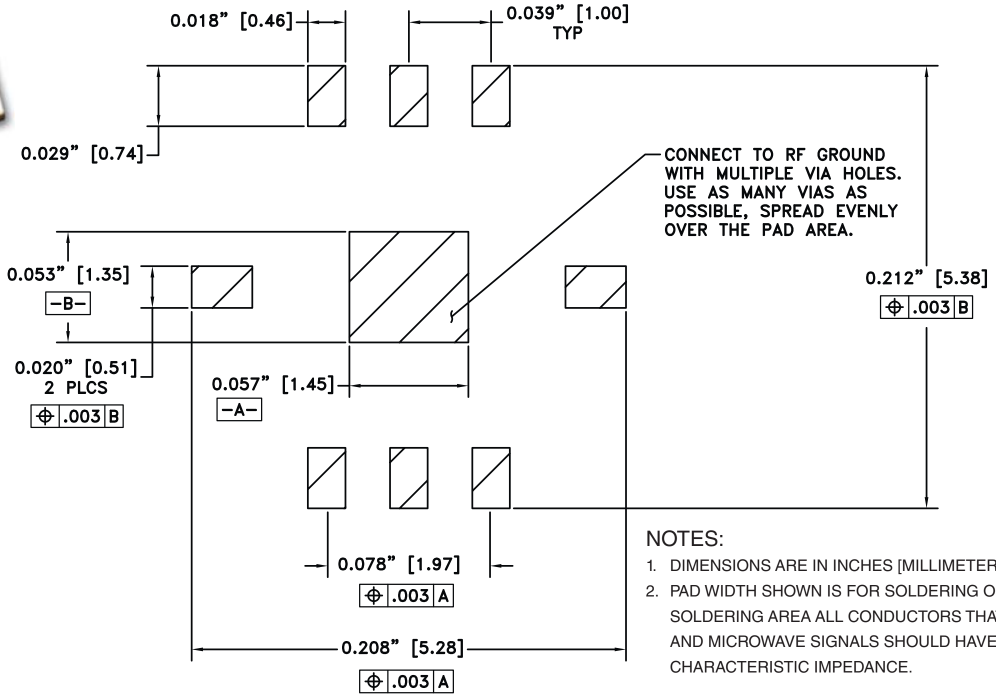
LM1 – LEADLESS CERAMIC HIGH FREQUENCY SMT PACKAGE

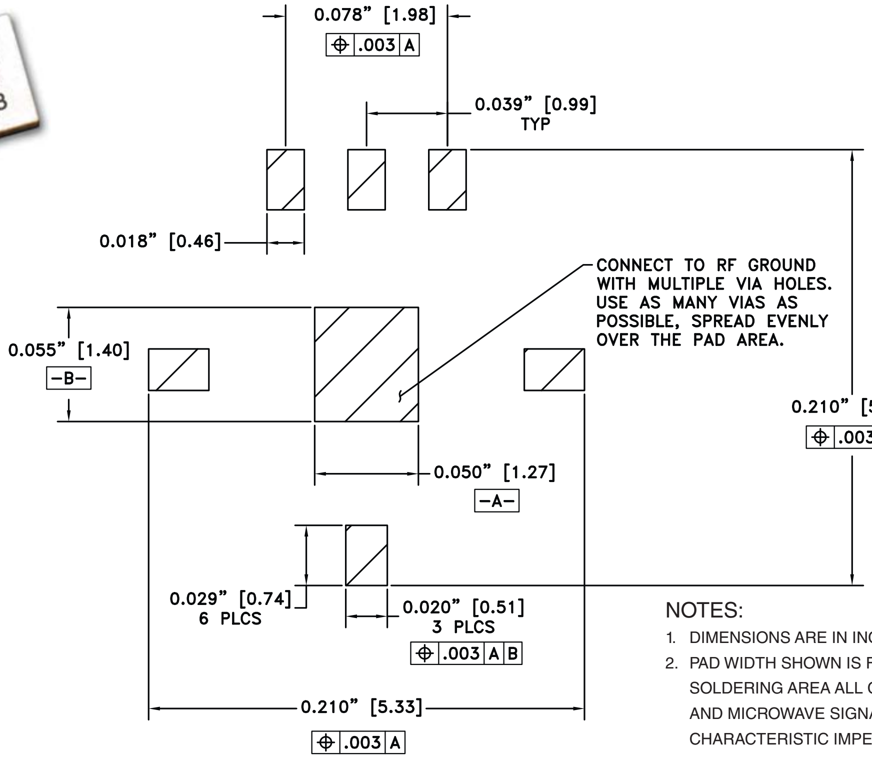
Suggested LM1 PCB Land Pattern



NOTES:

1. DIMENSIONS ARE IN INCHES [MILLIMETERS].
2. PAD WIDTH SHOWN IS FOR SOLDERING ONLY. BEYOND SOLDERING AREA ALL CONDUCTORS THAT CARRY RF AND MICROWAVE SIGNALS SHOULD HAVE 50 OHM CHARACTERISTIC IMPEDANCE.

Suggested LM3 PCB Land Pattern



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